RELIABILITY DELIVERED

AVOIDEVOID

Paste 1

Paste 2

Paste 3

Paste 4

Indium8.9HF

Indium10.1HF

Indium8.9HF Solder Paste

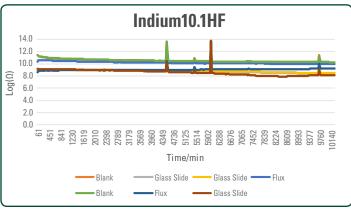
+) ELECTRICAL RELIABILITY

Indium8.9HF Superior Electrical Reliability	Enhanced SIR Requirements	Standard SIR (J-STD-004B) Requirements
Minimum SIR requirement	5,000M0hms	100MOhms
Time	1,000 hours	168 hours
Spacing	0.2mm	0.5mm
Voltage	10V, 50V	5V
SIR coupon	B52	B24

- Indium8.9HF shows no dendritic growth under high-power, low-standoff MOSFETs (as validated with automotive customers)
- Proven low ionics <<<1.56µgrams/sq cm
- Meets MS184-01 testing criteria

Indium10.1HF Solder Paste

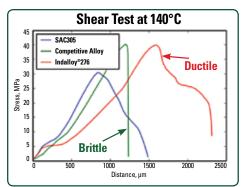
+) ELECTRICAL RELIABILITY

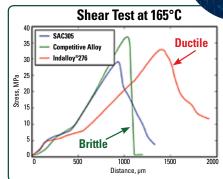


Glass Slide SIR is performed with the flux vehicle only to provide a worst-case scenario test. The glass slide is meant to mimic the bottom of a low standoff component. Reflowed solder paste would produce higher standoff and, therefore, higher SIR values.

Indalloy®276

The High-Reliability Automotive Alloy







RELIABILITY DELIVERED

Full Line of Materials for all Aspects of Assembly

Flux-Cored Wire

Circuit Board Assembly and Rework

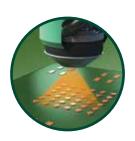
- Void-free, perfectly layer-wound package
- · Hand soldering and automated wire feed
- Widest range of flux-cored wire solders for both standard electronic assembly, as well as highly specialized needs

Core 230-RC

No-Spatter, No-Clean, REACH-Compliant Robotic Soldering Wire

CW-807

REACH-Compliant, Halogen-Free, No-Clean Flux-Cored Wire Used for automated and hand soldering



WF-9958

Wave Solder Flux

- Halogen-free per J-STD-004B
- · Light-colored, low-residue, rosin-free flux
- Residue for enhanced pin-testing performance
- Tested compatibility with HASL, Immersion Silver, ENIG, and OSP copper surfaces
- Tested for use with all common lead-free and tin-lead alloys

Test	Result
Color	Clear
Specific Gravity at 25°C (77°F) at 15.5°C (60°F)	0.798 0.805
Acid Value mgKOH/g flux mgKOH/g flux solids	28.5 571
Solids Content	4.99
Flash Point	12°C
J-STD-004B Flux Type	ORM0

<50ppm



Low-Temperature Solders (115 to 190°C)

Common Applications:

- Temperature-sensitive components
- Substrates that deform, melt, or delaminate at higher reflow temperatures
- Step-soldering
- CTE mismatch
- Moisture-sensitive components

Solder Forms:

Total Halogen

- Paste
- Preforms
- Solid Wire
- Spheres
- Ribbon/Foil



Contact our expert today: cnash@indium.com

Learn more: www.indium.com

From One Engineer To Another

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